- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Standard Plastic and Ceramic 300-mil DIPs
- Dependable Texas Instruments Quality and Reliability

	TYPICAL AVERAGE	TYPICAL
TYPE	PROPAGATION	TOTAL POWER
	DELAY TIME	DISSIPATION
'86	14 ns	150 mW
'LS86A	10 ns	30.5 mW
'S86	7 ns	250 mW

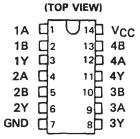
description

These devices contain four independent 2-input Exclusive-OR gates. They perform the Boolean functions $Y = A \oplus B = \overline{A}B + A\overline{B}$ in positive logic.

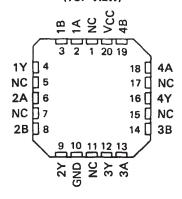
A common application is as a true/complement element. If one of the inputs is low, the other input will be reproduced in true form at the output. If one of the inputs is high, the signal on the other input will be reproduced inverted at the output.

The SN5486, 54LS86A, and the SN54S86 are characterized for operation over the full military temperature range of -55°C to 125°C. The SN7486, SN74LS86A, and the SN74S86 are characterized for operation from 0°C to 70°C.

SN5486, SN54LS86A, SN54S86 . . . J OR W PACKAGE SN7486 . . . N PACKAGE SN74LS86A, SN74S86 . . . D OR N PACKAGE



SN54LS86A, SN54S86 . . . FK PACKAGE (TOP VIEW)



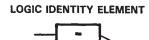
NC - No internal connection

exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.

EXCLUSIVE-OR

These are five equivalent Exclusive-OR symbols valid for an '86 or 'LS86A gate in positive logic; negation may be shown at any two ports.

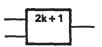


The output is active (low) if all inputs stand at the same logic level (i.e., $A \approx B$).



The output is active (low) if an even number of inputs (i.e., 0 or 2) are active.

ODD-PARITY ELEMENT

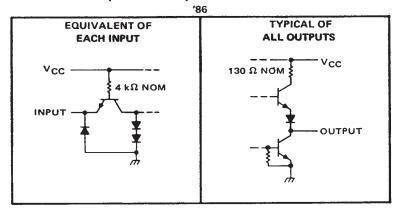


The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.

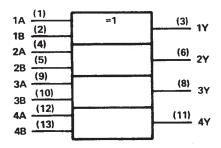
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



schematics of inputs and outputs



logic symbol†



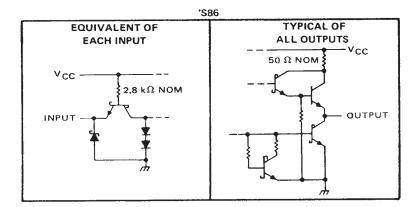
[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

POUIVALENT OF EACH INPUT VCC 12.5 kΩ NOM INPUT TYPICAL OF ALL OUTPUTS VCC 10.5 kΩ NOM NOM OUTPUT

FUNCTION TABLE

INP	UTS	OUTPUT
Α	В	Υ
L	L	L
L	Н	н
Н	L	н
Н	н	L

H = high level, L = low level



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)							 							7 V
Input voltage														
Operating free-air temperature range:	SN5486										- 5	55°C	to	125°C
	SN7486													
Storage temperature range														

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN5486	6		UNIT		
	MIN	NOM	MAX	MIN	NOM	MAX	CIVIT
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	٧
High-level output current, IOH			-800			-800	μΑ
Low-level output current, IOL			16			16	mA
Operating free-air temperature, TA	55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DARAMETER	TEST CONDITIONS†		SN5486	3		UNIT		
	PARAMETER	TEST CONDITIONS.	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
ViH	High-level input voltage		2			2			V
VIL	Low-level input voltage				8.0			0.8	V
VIK	Input clamp voltage	V _{CC} = MIN, I ₁ = -8 mA			-1.5			-1.5	V
.,	Wish Israel automatical	VCC = MIN, VIH = 2 V,	2.4	3.4		2.4	3.4		v
VOH	High-level output voltage	$V_{1L} = 0.8 \text{ V}, i_{OH} = -800 \mu\text{A}$	2.4	3.4		2.4	3.4		1
1/	Law level output voltage	V _{CC} = MIN, V _{IH} = 2 V		0.2	0.4		0.2	0.4	V
VOL	Low-level output voltage	V _{1L} = 0.8 V, 1 _{OL} = 16 mA		0,2	0.4		0.2	0.4	
1	Input current at maximum input voltage	V _{CC} = MAX, V _I = 5.5 V			1			1	mA
11H	High-level input current	V _{CC} = MAX, V ₁ = 2.4 V			40			40	μΑ
11L	Low-level input current	V _{CC} = MAX, V _I = 0.4 V			-1.6			-1.6	mA
los	Short-circuit output current§	V _{CC} = MAX	20		-55	-18		-55	mA
¹cc	Supply current	V _{CC} = MAX, See Note 2		30	43		30	50	mA

For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER¶	FROM (INPUT)	TEST COM	IDITIONS	MIN	TYP	MAX	UNIT
tPLH	A or B	Oah as is such law.	C _L = 15 pF,		15	23	ns
tPHL t	AOIB	Other input low	_		11	17	
tPLH	A or B	Oshovinova biob	R _L = 400 Ω , See Note 3		18	30	ns
tPHL	AOIB	Other input high	See Note 5		13	22	

 $[\]P_{tplH}$ = propagation delay time, low-to-high-level output



 $^{^{\}ddagger}$ All typical values are at $V_{CC} = 5 \text{ V}$, $T_{A} = 25^{\circ}\text{C}$.

[§]Not more than one output should be shorted at a time.

NOTE 2: ICC is measured with the inputs grounded and the outputs open.

tpHL = propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

SN5486, SN54LS86A, SN54S86 SN7486, SN74LS86A, SN74S86 **QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES**

SDLS124 - DECEMBER 1972 - REVISED MARCH 1988

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)							•							7 V
Input voltage				 							•			7 V
Operating free-air temperature range: SN54LS86	Α.										-5	5°C	; to	125°C
SN74LS86	Δ.											o°	C to	o 70°C
Storage temperature range														

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	S	N54LS	36A	SI	N74LS8	6A	UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	DIVIT
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			-400			-400	μА
Low-level output current, IOL			4			8	mA
Operating free-air temperature, TA	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			NO TIONS	SI	154LS8	6A	SI	174LS8	6A	UNIT
	PARAMETER	IEST CO	NDITIONS	MIN	TYP‡	MAX	MIN	TYP‡	MAX	101411
VIH	High-level input voltage			2			2			\ \ _
VIL	Low-level input voltage					0.7			0.8	V
VIK	Input clamp voltage	V _{CC} = MIN,	I ₁ = -18 mA			-1.5			-1.5	V
VOH	High-level output voltage	V _{CC} = MIN, V _{IL} = V _{IL} max	V _{IH} = 2 V, , I _{OH} = -400 μA	2.5	3.4		2.7	3.4		٧
Voi	Low-level output voltage	V _{CC} = MIN, V _{IH} = 2 V,	1 _{OL} = 4 mA		0.25	0.4		0.25	0.4	V
* OL	2011 letter output to kuge	VIL = VILmax	I _{OL} = 8 mA					0.35	0.5	
11	Input current at maximum input voltage	V _{CC} = MAX,	V _I = 7 V			0.2			0.2	mA
ЧН	High-level input current	V _{CC} = MAX,	V _I = 2.7 V			40			40	μА
I _I L	Low-level input current	V _{CC} = MAX,	V ₁ = 0.4 V			-0.8			-0.8	mA
los	Short-circuit output current§	V _{CC} = MAX		- 20		- 100	- 20		- 100	mA
Icc	Supply current	V _{CC} = MAX,	See Note 2		6.1	10		6.1	10	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type. ‡ All typical values are at $V_{CC} = 5 \text{ V}$, $T_{A} = 25^{\circ}\text{C}$.

NOTE 2: I_{CC} is measured with the inputs grounded and the outputs open.

switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER¶	FROM (INPUT)	TEST CON	IDITIONS	MIN	TYP	MAX	UNIT
tpLH	A or B	Out as in suct low	C 15 pE		12	23	ns
t _{PHL}	A Of B	Other input low	$C_L = 15 pF$, $R_L = 2 kQ$,		10	17	
tpLH	A or B	Other input high	See Note 3		20	30	ns
tPHL	AOIB	Other input night	See Note 5		13	22	

[¶]tpLH = propagation delay time, low-to-high-level output



[§]Not more than one output should be shorted at a time.

tpHL = propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)		 7 V
Input voltage		 5.5 V
Operating free-air temperature range: SN5	4586	 55°C to 125°C
SN7	4586	 0°C to 70°C
Storage temperature range		 -65° C to 150° C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54S8	6		SN74S8	6	UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	UNII
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			1			-1	mA
Low-level output current, IOL			20			20	mA
Operating free-air temperature, TA	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS†	1	SN54S8	6	:	6	UNIT	
PARAMETER		TEST CONDITIONS.	MIN	TYP‡	MAX	MIN	TYP [‡]	MAX	0.4.1
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.8			8.0	V
VIK	Input clamp voltage	V _{CC} = MIN, I _I = -18 mA			-1.2		-	-1.2	V
V _{OH}	High-level output voltage	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OH} = -1 mA	2.5	3.4		2.7	3.4		٧
VOL	Low-level output voltage	V _{CC} = MIN, V _{IH} = 2 V V _{IL} = 0.8 V, I _{OL} = 20 mA			0.5			0.5	٧
T ₁	Input current at maximum input voltage	V _{CC} = MAX, V _I = 5.5 V			1			1	mA
Чн	High-level input current	V _{CC} = MAX, V _I = 2.7 V			50			50	μА
TIL	Low-level input current	V _{CC} = MAX, V _I = 0.5 V	1		-2			-2	mA
los	Short-circuit output current§	V _{CC} = MAX	-40		-100	-40		-100	mA
Icc	Supply current	V _{CC} = MAX, See Note 2		50	75		50	75	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

NOTE 2: I_{CC} is measured with the inputs grounded and the outputs open.

switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER¶	FROM (INPUT)	TEST COM	IDITIONS	MIN	TYP	MAX	UNIT
^t PLH	A or B	Other input low	0 - 15 - 5		7	10.5	ns
[†] PHL	AUIB	Other input low	C _L = 15 pF,		6.5	10	
tpLH	A or B	Other input high	$R_L = 280 \Omega$, See Note 3		7	10.5	ns
tPHL	AOIB	Other input night	See Note 3		6.5	10	L

[¶]tpLH = propagation delay time, low-to-high-level output



 $[\]ddagger$ All typical values are at V_{CC} = 5 V, T_A = 25°C. § Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

tpHL = propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



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PACKAGING INFORMATION

JM8851007501BDA ACTIVE CDIP J 14	Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	n MSL Peak Temp (3)
JM38510/07501BDA	JM38510/07501BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30502B2A	JM38510/07501BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30502B2A	JM38510/07501BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30502BCA	JM38510/30502B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30502BCA	JM38510/30502B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30502BDA ACTIVE CFP W	JM38510/30502BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30502BDA ACTIVE CFP W 14	JM38510/30502BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN5486J ACTIVE CDIP J 14 1 TBD A42 N / A for Pkg Type	JM38510/30502BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN54LS86AJ ACTIVE CDIP J 14 1 TBD A42 N / A for Pkg Type	JM38510/30502BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN54LS86AJ ACTIVE CDIP J 14 1 TBD A42 N / A for Pkg Type	SN5486J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54LS86AJ ACTIVE CDIP J 14 1 TBD A42 N / A for Pkg Type	SN5486J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S86J ACTIVE CDIP J 14 1 TBD A42 N / A for Pkg Type	SN54LS86AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S86J ACTIVE CDIP J 14 1 TBD A42 N / A for Pkg Type	SN54LS86AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN7486N	SN54S86J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN7486N	SN54S86J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN74B6N3	SN7486N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS86AD	SN7486N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS86AD ACTIVE SOIC D 14 50 Green (RoHS & CU NIPDAU Level-1-260C-UNLIM no Sb/Br)	SN7486N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS86AD ACTIVE SOIC D 14 50 Green (RoHS & CU NIPDAU Level-1-260C-UNLIM no Sb/Br)	SN7486N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS86ADE4	SN74LS86AD	ACTIVE	SOIC	D	14	50		CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADE4	SN74LS86AD	ACTIVE	SOIC	D	14	50	•	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADG4	SN74LS86ADE4	ACTIVE	SOIC	D	14	50		CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADG4	SN74LS86ADE4	ACTIVE	SOIC	D	14	50		CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADR	SN74LS86ADG4	ACTIVE	SOIC	D	14	50		CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADR ACTIVE SOIC D 14 2500 Green (RoHS & CU NIPDAU Level-1-260C-UNLIM no Sb/Br) SN74LS86ADR ACTIVE SOIC D 14 2500 Green (RoHS & CU NIPDAU Level-1-260C-UNLIM no Sb/Br) SN74LS86ADRE4 ACTIVE SOIC D 14 2500 Green (RoHS & CU NIPDAU Level-1-260C-UNLIM no Sb/Br) SN74LS86ADRE4 ACTIVE SOIC D 14 2500 Green (RoHS & CU NIPDAU Level-1-260C-UNLIM no Sb/Br) SN74LS86ADRG4 ACTIVE SOIC D 14 2500 Green (RoHS & CU NIPDAU Level-1-260C-UNLIM no Sb/Br) SN74LS86ADRG4 ACTIVE SOIC D 14 2500 Green (RoHS & CU NIPDAU Level-1-260C-UNLIM no Sb/Br) SN74LS86AN ACTIVE PDIP N 14 25 Pb-Free CU NIPDAU N / A for Pkg Type	SN74LS86ADG4	ACTIVE	SOIC	D	14	50		CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADRE4	SN74LS86ADR	ACTIVE	SOIC	D	14	2500	,	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADRE4 ACTIVE SOIC D 14 2500 Green (RoHS & CU NIPDAU Level-1-260C-UNLIM no Sb/Br) SN74LS86ADRE4 ACTIVE SOIC D 14 2500 Green (RoHS & CU NIPDAU Level-1-260C-UNLIM no Sb/Br) SN74LS86ADRG4 ACTIVE SOIC D 14 2500 Green (RoHS & CU NIPDAU Level-1-260C-UNLIM no Sb/Br) SN74LS86ADRG4 ACTIVE SOIC D 14 2500 Green (RoHS & CU NIPDAU Level-1-260C-UNLIM no Sb/Br) SN74LS86AN ACTIVE PDIP N 14 25 Pb-Free CU NIPDAU N / A for Pkg Type	SN74LS86ADR	ACTIVE	SOIC	D	14	2500	`	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADRG4	SN74LS86ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS &	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADRG4 ACTIVE SOIC D 14 2500 Green (RoHS & CU NIPDAU Level-1-260C-UNLIM no Sb/Br) SN74LS86ADRG4 ACTIVE SOIC D 14 2500 Green (RoHS & CU NIPDAU Level-1-260C-UNLIM no Sb/Br) SN74LS86AN ACTIVE PDIP N 14 25 Pb-Free CU NIPDAU N / A for Pkg Type	SN74LS86ADRE4	ACTIVE	SOIC	D	14	2500		CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADRG4 ACTIVE SOIC D 14 2500 Green (RoHS & CU NIPDAU Level-1-260C-UNLIM no Sb/Br) SN74LS86AN ACTIVE PDIP N 14 25 Pb-Free CU NIPDAU N / A for Pkg Type	SN74LS86ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS &	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86AN ACTIVE PDIP N 14 25 Pb-Free CU NIPDAU N / A for Pkg Type	SN74LS86ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS &	CU NIPDAU	Level-1-260C-UNLIM
(RoHS)	SN74LS86AN	ACTIVE	PDIP	N	14	25	Pb-Free	CU NIPDAU	N / A for Pkg Type
SN74LS86AN ACTIVE PDIP N 14 25 Pb-Free CU NIPDAU N / A for Pkg Type	SN74LS86AN	ACTIVE	PDIP	N	14	25		CU NIPDAU	N / A for Pkg Type



PACKAGE OPTION ADDENDUM

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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³
						(RoHS)		
SN74LS86AN3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS86AN3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS86ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS86ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS86ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS86ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS86ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS86ANSRG4	ACTIVE	so	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS86ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74S86D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74S86D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74S86DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74S86DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74S86DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74S86DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74S86N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S86N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S86N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S86N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S86NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S86NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S86NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74S86NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74S86NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74S86NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLII
SN74S86NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI

PACKAGE OPTION ADDENDUM

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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74S86NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ5486J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ5486J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ5486W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ5486W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS86AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS86AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS86AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS86AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS86AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS86AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S86FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S86FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S86J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54S86J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54S86W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S86W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS86ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS86ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74S86NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS86ADR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LS86ANSR	SO	NS	14	2000	346.0	346.0	33.0
SN74S86NSR	SO	NS	14	2000	346.0	346.0	33.0

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

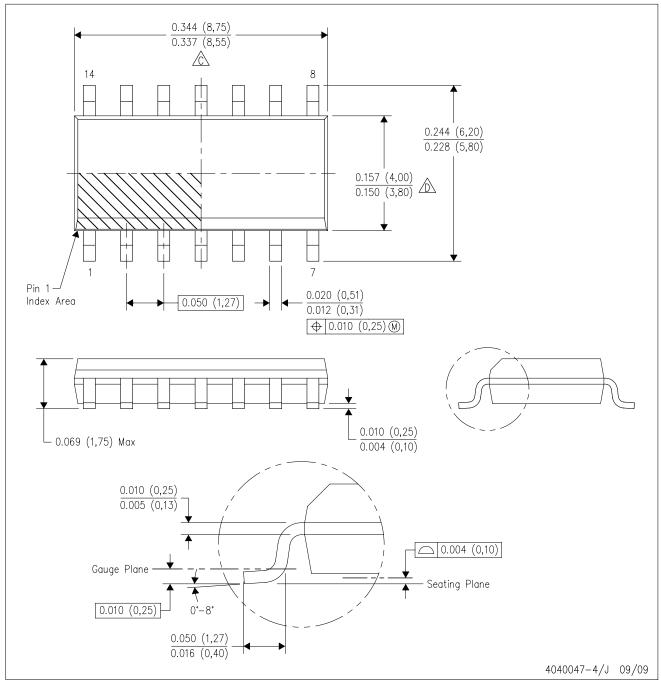


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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